

Electronic Patent Application Fee Transmittal

Application Number:	10767136			
Filing Date:	28-Jan-2004			
Title of Invention:	SEMICONDUCTOR PACKAGE HAVING THERMAL INTERFACE MATERIAL (TIM)			
First Named Inventor:	Joong-Hyun Baek			
Filer:	Alexander Charles Johnson/Li Mei Vermilya			
Attorney Docket Number:	9903-085			

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Publ. Fee- early, voluntary, or normal	1504	1	300	300
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Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl issue fee	1501	1	1400	1400
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700